

PCB - ME-IO 18,8/28 TBUS DEV-PCB - 2202548

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Perforated grid board for the ME-IO 18,8 DEV-KIT; for HSCH 2,5 header; ideal for manual soldering



Why buy this product

- Hole matrix PCB for self-assembly
- Assembly area approx. 3,400 mm²
- Hole matrix dimension: 2.54 mm

Key Commercial Data

Packing unit	1 pc
GTIN	 4 055626 142609
Weight per Piece (excluding packing)	16.4 g
Custom tariff number	85340011
Country of origin	Denmark
Product key	ACHICB

Technical data

General

Housing type	Component housing
Housing material	FR 4-21
Color	green

Ambient conditions

Ambient temperature (operation)	110 °C (depending on power dissipation)
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Dimensions

Pitch	2.54 mm
	5 mm

Technical data

Flammability rating according to UL 94	V0
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Classifications

eCl@ss

eCl@ss 5.1	27379201
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ETIM

ETIM 4.0	EC002498
ETIM 5.0	EC001031

Accessories

Additional products

Electronic housing - ME-IO 18,8 DEV-KIT KMGY - 2202527



DEV-KIT ME-IO: contains 1 x ME-IO 18,8 housing and pluggable connection technology (HSCH with HSCP), supplied in individual parts

Plug - ME 18,8 TBUS 1,5/5 VPE1 KMGY - 2202549



Bus connector to connect ME-IO modules on the DIN rail; suitable for ME-IO DEV-KITS; contains ME 18,8 TBUS 1,5/ 5